

WEIDACHENG INDUSYRY CO.,LTD

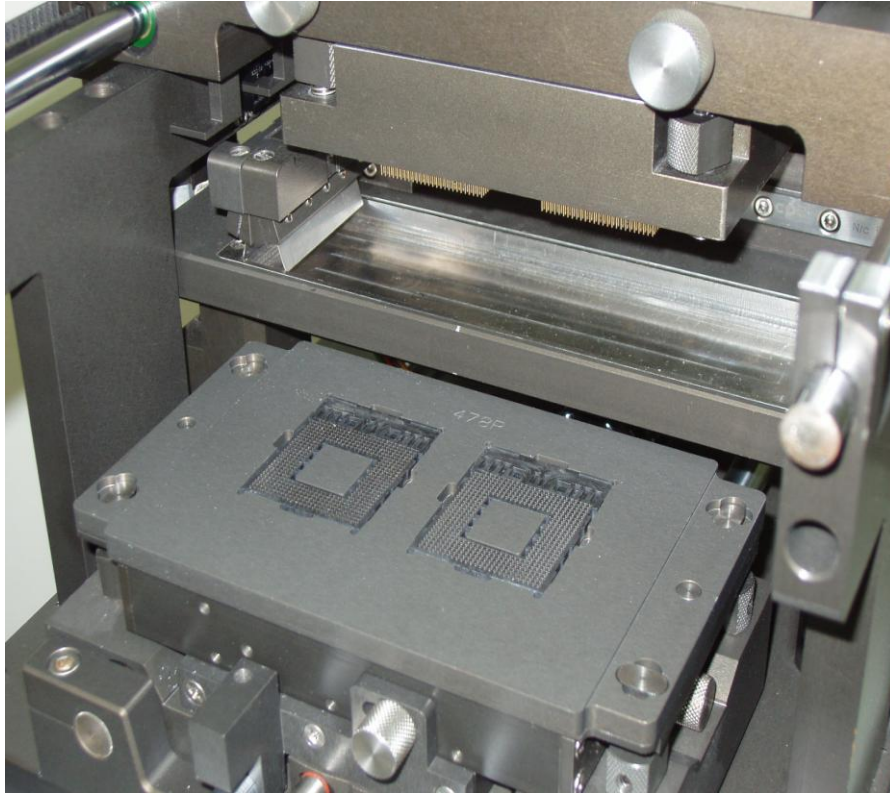
<http://www.bga500.com.tw> [E-mail:bga500@ms23.hinet.net](mailto:bga500@ms23.hinet.net)

TRANSFER-PRINT SOLDER BALL MOUNTER BU-570

Ball placement capability: Φ 0.35 ~ Φ 0.76 Ball placement range:L-65mm.W-80mm



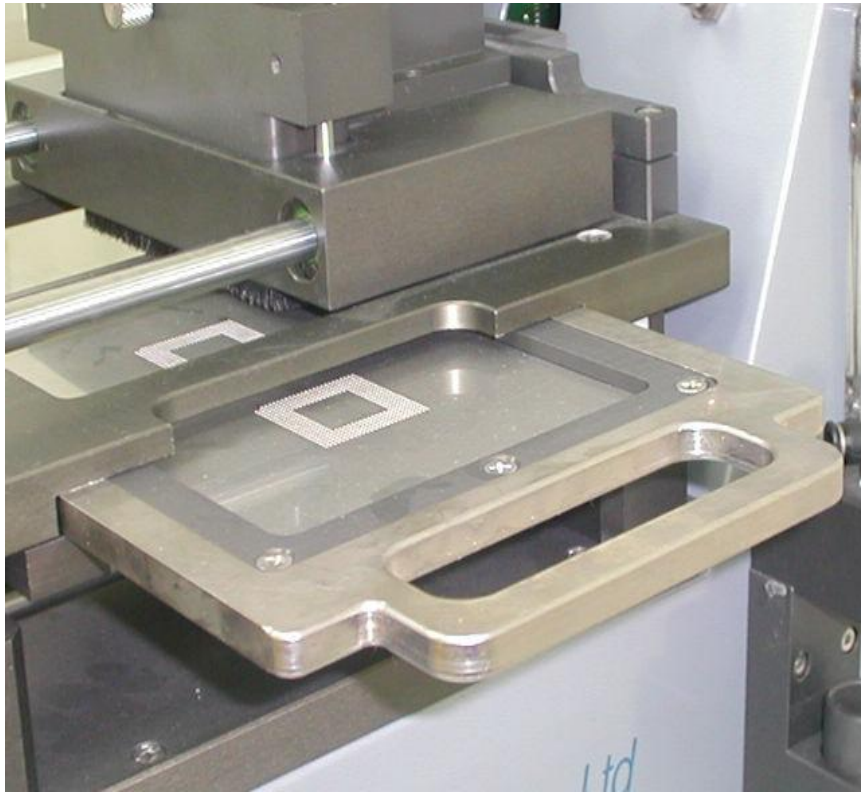
X-Y- θ Theta positioning slider with micrometers adjustment & BGA fixtures.



Touch-Screen usage & setting



Drawable solder ball mask cassette base.



Solder ball collecting bottle base.
(Ball cleaning device)

